

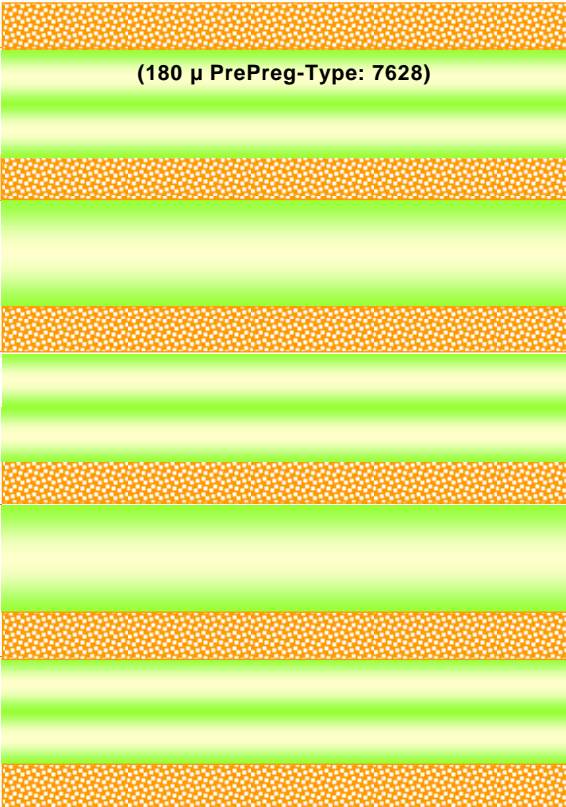
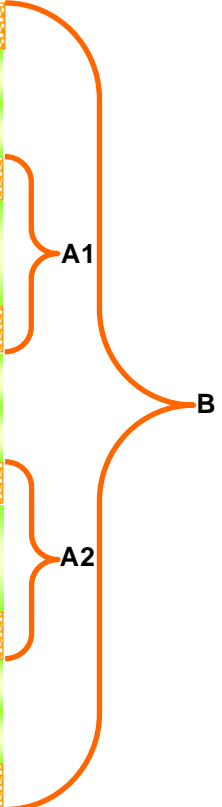
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 225 FR4 35 L41.70 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_225_FR4_35_L41.70_p18

Layers	in μ	Material	Build-Up	Assembly		
Layer-1	35 μ	Copper				
	180 μ	Prepreg			(180 μ PrePreg-Type: 7628)	
Layer-2	180 μ	Prepreg				A1
	70 μ	Copper				
Layer-3	410 μ	L-FR4				A2
	70 μ	Copper				
Layer-4	180 μ	Prepreg				B
	180 μ	Prepreg				
Layer-5	70 μ	Copper				A1
	410 μ	L-FR4				
Layer-99	70 μ	Copper		A2		
	180 μ	Prepreg				
	180 μ	Prepreg		B		
	35 μ	Copper				

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